Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

2SK3117

Chopper Regulator DC-DC Converter and Motor Drive Applications

• Low drain—source ON resistance : RDS (ON) = 0.21Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 17 S$ (typ.) • Low leakage current : IDSS = $100 \mu A$ (max) (VDSS = 500 V) • Enhancement mode : $V_{th} = 2.0 \sim 4.0 V$ (VDS = 10 V, ID = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	500	V
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	500	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	20	Α
	Pulse (Note 1)	I _{DP}	80	Α
Drain power dissipation	n (Tc = 25°C)	P _D	150	W
Single pulse avalanche energy (Note 2)		E _{AS}	960	mJ
Avalanche current		I _{AR}	20	Α
Repetitive avalanche energy (Note 3)		E _{AR}	15	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C

15.9MAX.

11.0

12.0

1. GATE
2. DRAIN (HEAT SINK)
3. SOURCE

JEDEC

JEITA

TOSHIBA

2-16H1B

Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 4.08 mH, R_{G} = 25 Ω , I_{AR} = 20 A

Note 3: Repetitive rating pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device.

Please handle with caution.



Electrical Characteristics (Ta = 25°C)

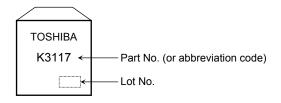
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		_	100	μΑ
Drain-source br voltage	eakdown	V _(BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	_	ı	V
Gate threshold v	roltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 10 A	_	0.21	0.27	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 10 A	10	17	_	S
Input capacitano	e	C _{iss}			3720	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		340	_	pF
Output capacitance		Coss			1165	_	
Switching time	Rise time	tr	V_{GS} V_{OV} V_{DD} V_{DD} V_{DD} V_{DD}	_	30	_	
	Turn-on time	t _{on}		_	70	_	no
	Fall time	t _f		_	50	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm w} = 10 \mu \rm s$	_	290	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	80	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		48	_	nC
Gate-drain ("miller") charge		Q_{gd}		_	32	_	

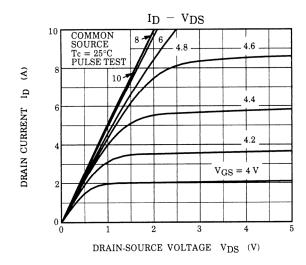
Source-Drain Ratings and Characteristics (Ta = 25°C)

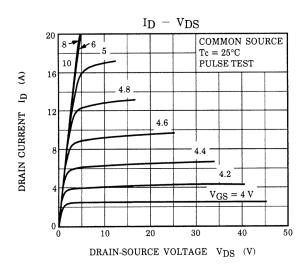
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	20	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	80	А
Forward voltage (diode)	V _{DSF}	V _{DR} = 20 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 20 A, V _{GS} = 0 V		540	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / μs		5.4	_	μC

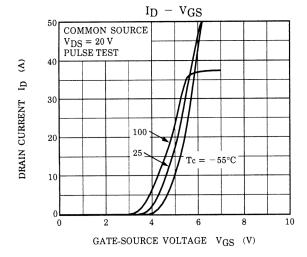
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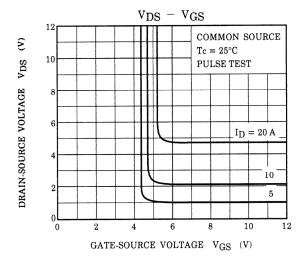
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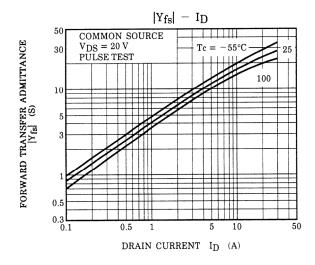


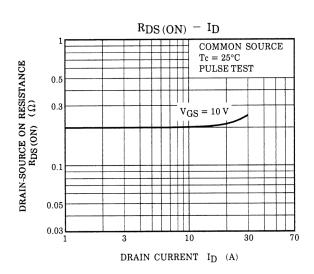


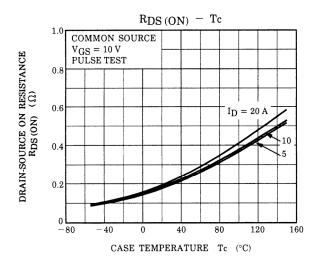


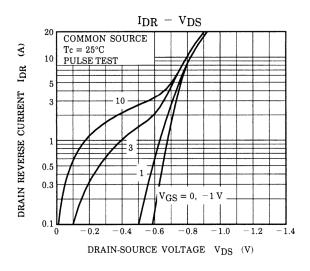


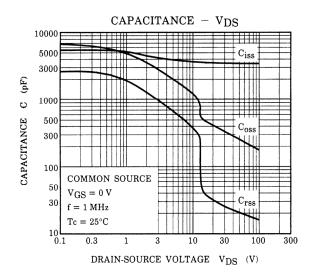


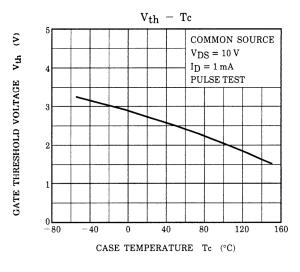


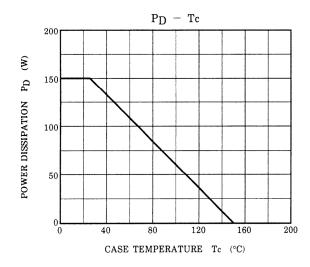


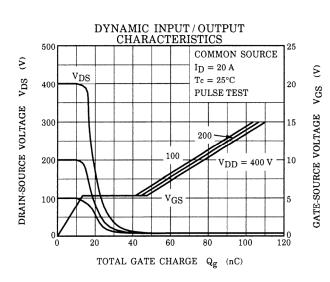


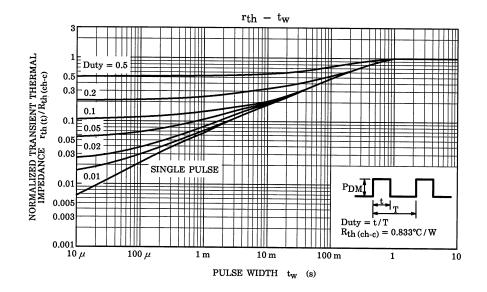


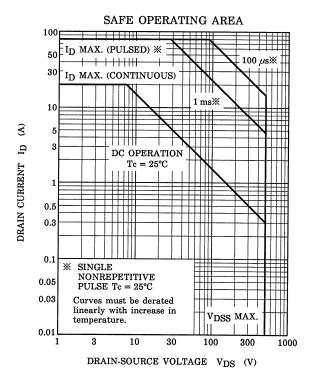


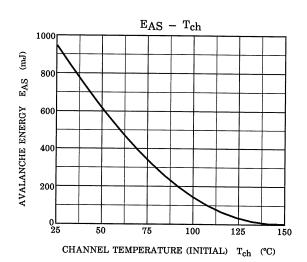


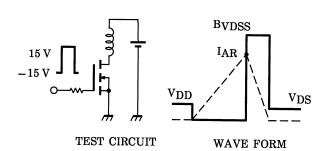












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 4.08~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - V_{DD}} \right) \end{aligned}$$

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20070701-EN

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